Amendments to Claims

1. (Currently Amended) An organic electronic device comprising a heat sink, wherein:

the heat sink ~~having~~ has a side with a pattern that extends at least partially through a thickness of the heat sink~~, wherein:~~;

the heat sink has a thickness no greater than 9 mm; and

the heat sink is attached to an array within ~~an~~ the organic electronic device.

2. (Currently Amended) The ~~heat sink~~ organic electronic device of claim 1, wherein at least one side of the heat sink has a pattern that extends partially, but not completely through the heat sink.

3. (Cancelled)

4. (Currently Amended) The ~~heat sink~~ organic electronic device of claim 2, wherein the heat sink has a thickness no greater than 500 microns.

5. (Currently Amended) The ~~heat sink~~ organic electronic device of claim 2, wherein the heat sink lies within 90 μm of an organic active layer of the organic electronic device.

6. (Currently Amended) The ~~heat sink~~ organic electronic device of claim 2, wherein the side with the pattern has a black surface.

7. (Currently Amended) The ~~heat sink~~ organic electronic device for claim 2, wherein the organic electronic device is designed to be at least one of an outdoor display and a lighting panel.

8. (Currently Amended) The ~~heat sink~~ organic electronic device of claim 1, wherein the side with the pattern is black.

9. (Currently Amended) An organic electronic device comprising a heat sink, wherein:

the heat sink has ~~having~~ a side with a pattern that extends at least partially through a thickness of the heat sink~~, wherein~~;

the heat sink has a ratio of area:thickness, as seen from a plan view, of at least 500:1 when the area and thickness are expressed in units of mm^2 and mm, respectively; and

the heat sink is attached to an array within ~~an~~ the organic electronic device.

10. (Currently Amended) The ~~heat sink~~ organic electronic device of claim 9, wherein at least one side of the heat sink has a pattern that extends partially, but not completely through the heat sink.

11. (Cancelled)

12. (Currently Amended) The ~~heat sink~~ organic electronic device of claim 10, wherein the heat sink has a thickness no greater than 500 microns.

13. (Currently Amended) The ~~heat sink~~ organic electronic device of claim 10, wherein the ratio of area:thickness is at least 11,000:1.

14. (Currently Amended) The ~~heat sink~~ organic electronic device of claim 10, wherein the heat sink lies within 90 μm of an organic active layer of the organic electronic device.

15. (Currently Amended) The ~~heat sink for~~ organic electronic device of claim 14, wherein the organic electronic device is designed to be at least one of an outdoor display and a lighting panel.

16. (Currently Amended) The ~~heat sink~~ organic electronic device of claim 10, wherein the side with the pattern has a black surface.